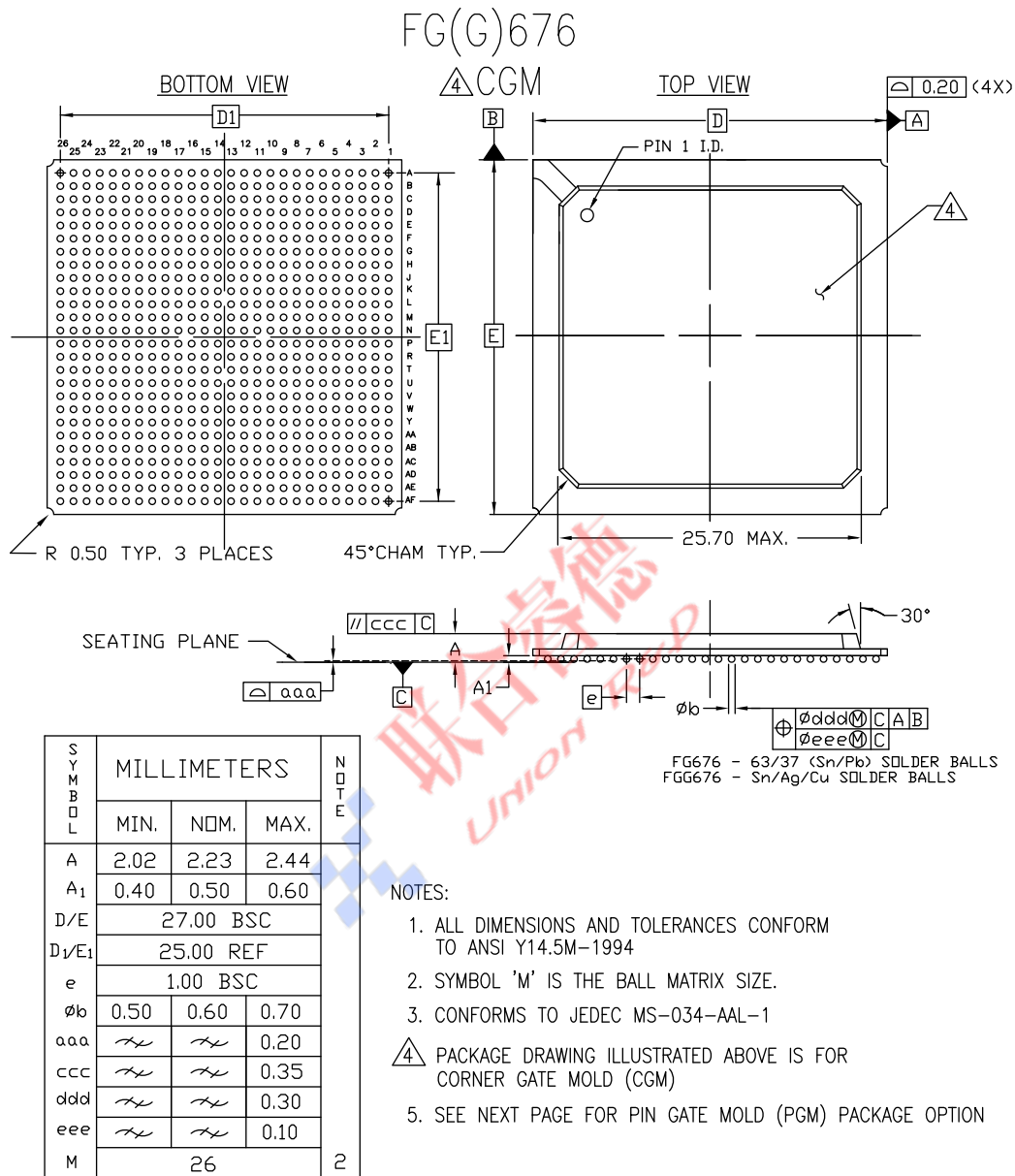


676-Ball Fine-Pitch BGA (FG676/FGG676) Package



pk035_01_032114

Figure 1: Corner Gate Mold Option, FG676/FGG676 Package

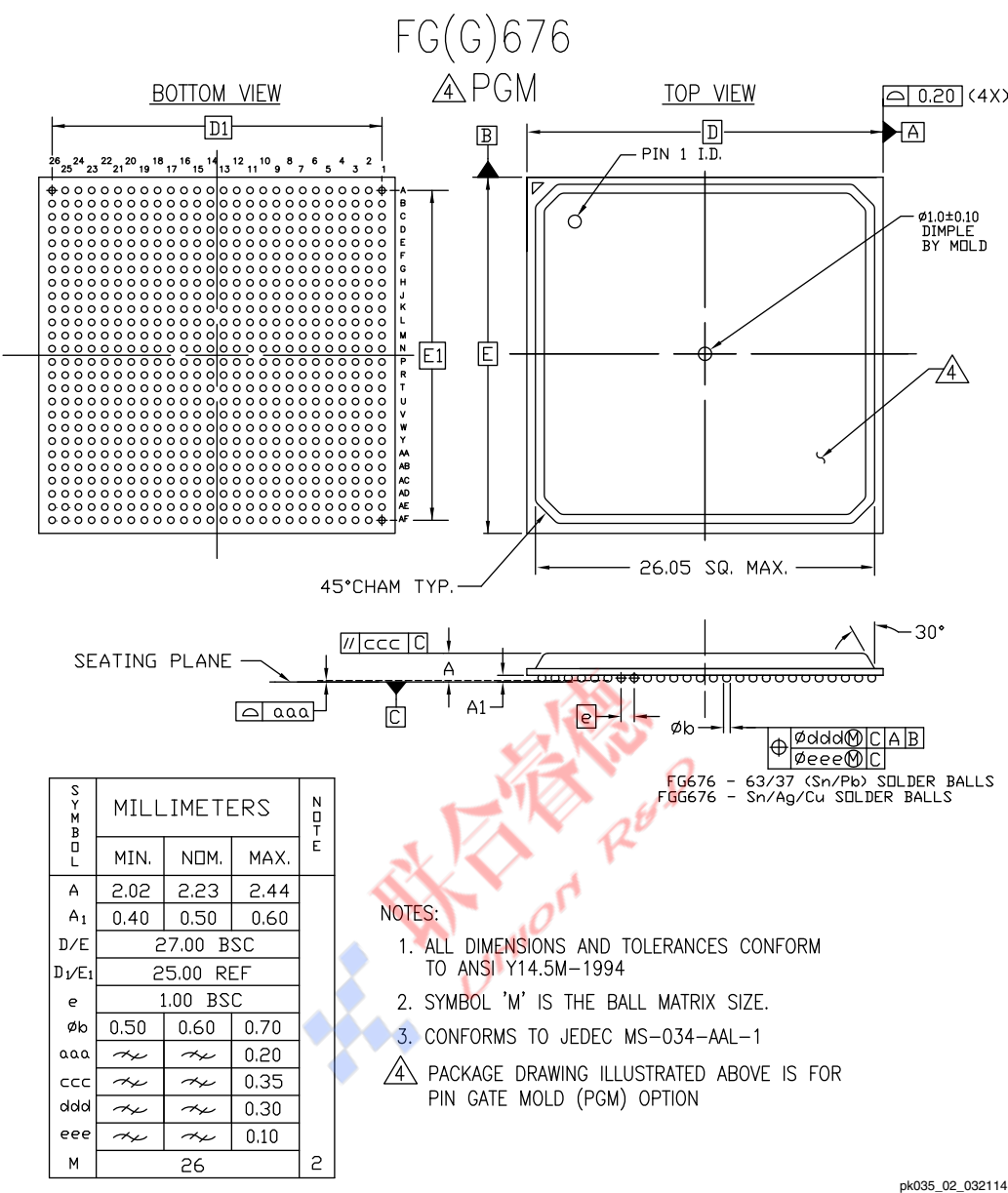


Figure 2: Pin Gate Mold Option, FG676/FGG676 Package

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/15/2011	1.3	Revised tolerances for symbol A.
04/04/2014	1.4	Added Figure 2, pin gate mold package as described in XCN12023.

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